

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	"6267649".pn. and wiring	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 09:43
L2	0	"6267649".pn. and wire	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 09:43
L3	1	"6267649".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 10:00
L4	6118	wiring same (CMP or polish or polishing)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:46
L5	3656	4 and ((etch or etching or pattern or patterning) with wiring)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 10:01
L6	2175	5 and @ay<="2001"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 10:01
L7	1917	6 and semiconductor	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 10:02
L8	456	7 and edge	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 10:08
L9	341	8 and (mask or resist or photo\$1resist)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 10:50
L10	164	9 and @py<="2001"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 10:50
L11	52	10 and (edge with (polish or polishing or cmp or etch or etching or remove or removing))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:03
L12	1	"5426073".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:03
L13	18	("5426073").URPN.	USPAT	OR	ON	2005/03/21 11:29
L14	1	"6150696".pn.	USPAT	OR	ON	2005/03/21 11:29
L15	4	("4700461"   "5116771"   "5597410"   "5834812").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/21 11:34
L16	344	Yano-Hiroyuki.in.	US-PGPUB; USPAT; USOCR; JPO	OR	ON	2005/03/21 11:34

L17	108	16 and wiring	US-PGPUB; USPAT; USOCR; JPO	OR	ON	2005/03/21 11:34
L18	77	17 and (polish or polishing or cmp)	US-PGPUB; USPAT; USOCR; JPO	OR	ON	2005/03/21 11:35
L19	46	18 and @ay<="2001"	US-PGPUB; USPAT; USOCR; JPO	OR	ON	2005/03/21 11:39
L20	1	"2000163045"	US-PGPUB; USPAT; USOCR; JPO	OR	ON	2005/03/21 11:39
L21	12706	(CMP or polish or polishing or etch\$3 or remov\$3) with edge with (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:47
L22	9153	21 and semiconductor	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:47
L23	1403	22 and wiring	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:47
L24	624	23 and (polish or polishing or cmp)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:48
L25	350	24 and @ay<="2001"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:48
L26	152	25 and ((polish or polishing or cmp) same wiring)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/21 11:48
S1	49122	(cmp or polish or polishing or planarize or planarizing) and (edge or pivot)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/30 11:10
S2	173	(((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) with (edge or pivot))) and @ay<="2001") and (slurry or abrasive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/30 11:11

S3	461	((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) same (edge or pivot))) and (slurry or abrasive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/30 11:11
S4	461	((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) same (edge or pivot))) and (slurry or abrasive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/30 11:16
S5	29472	(cmp or polish or polishing or planarize or planarizing) and (edge or pivot)	USPAT	OR	ON	2005/03/18 17:14
S6	12603	((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor	USPAT	OR	ON	2004/05/05 11:09
S7	6238	(((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)	USPAT	OR	ON	2004/05/05 11:09
S8	1126	((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) same (edge or pivot))	USPAT	OR	ON	2004/05/05 11:11
S9	485	((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) with (edge or pivot))	USPAT	OR	ON	2004/05/05 11:11
S10	457	((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) with (edge or pivot))) and @ay<="2001"	USPAT	OR	ON	2004/05/05 11:12

S11	284	(((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) same (edge or pivot))) and (slurry or abrasive)	USPAT	OR	ON	2004/09/30 11:16
S12	145	(((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) with (edge or pivot))) and @ay<="2001") and (slurry or abrasive)	USPAT	OR	ON	2004/09/30 11:10
S13	9	("5233218"   "5258323"   "5340435"   "5494849"   "5719426"   "5973365"   "5982003"   "6118152"   "6294478").PN.	USPAT	OR	ON	2004/05/05 11:40
S14	3	((("6663468") or ("6596087") or ("6563172")).PN.	USPAT; USOCR	OR	OFF	2004/05/05 12:57
S15	1	("6379782").PN.	USPAT; USOCR	OR	OFF	2004/05/05 14:38
S16	1	"6091130".PN.	USPAT	OR	ON	2004/05/05 12:57
S17	61	Iguchi-Manabu.in.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2004/05/05 14:38
S18	19	Iguchi-Manabu.in. and semiconductor	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2004/05/05 14:38
S19	1	"6091130".PN.	USPAT	OR	ON	2004/05/05 14:41

S20	139	(((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) same (edge or pivot))) and (slurry or abrasive)) not ((((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) with (edge or pivot))) and @ay<="2001") and (slurry or abrasive))	USPAT	OR	ON	2004/05/05 15:20
S21	10	("5409569"   "6136708"   "6162301"   "6165956"   "6261849"   "6287477"   "6294027"   "6303551"   "6322598"   "6387190"   "2001/0029104").PN.	USPAT	OR	ON	2004/05/05 15:01
S22	1	Yoshihisa-Matsubara.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/05/05 15:21
S23	103	Matsubara-Yoshihisa.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/05/05 15:24
S24	99	Matsubara-Yoshihisa.in. and semiconductor	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/05/05 15:22
S25	20	(Matsubara-Yoshihisa.in. and semiconductor) and polishing	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/05/05 15:22
S26	22	Takewaki-Toshiyuki.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/05/05 15:24
S27	4196	(cmp or polish or polishing or planarize or planarizing) with (edge or bevel\$3)	USPAT	OR	ON	2004/05/05 15:42
S28	1887	((cmp or polish or polishing or planarize or planarizing) with (edge or bevel\$3)) and semiconductor and @ay<="2001"	USPAT	OR	ON	2004/05/05 15:34

S29	1217	((cmp or polish or polishing or planarize or planarizing) with (edge or bevel\$3)) and semiconductor and @ay<="2001") and (slurry or abrasive)	USPAT	OR	ON	2004/05/05 15:35
S30	178	(((((cmp or polish or polishing or planarize or planarizing) with (edge or bevel\$3)) and semiconductor and @ay<="2001") and (slurry or abrasive)) and (mask or hard\$1mask)	USPAT	OR	ON	2004/05/05 15:35
S31	176	(((((cmp or polish or polishing or planarize or planarizing) with (edge or bevel\$3)) and semiconductor and @ay<="2001") and (slurry or abrasive)) and (mask or hard\$1mask)) not (((((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) same (edge or pivot))) and (slurry or abrasive)) not (((((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) with (edge or pivot))) and @ay<="2001") and (slurry or abrasive))) or Matsubara-Yoshihisa.in.)	USPAT	OR	ON	2004/05/05 15:35
S32	1424	(cmp or polish or polishing or planarize or planarizing) and (chamfer\$3)	USPAT	OR	ON	2004/05/05 15:42
S33	1428	(cmp or polish or polishing or planarize or planarizing) and (chamfer\$4)	USPAT	OR	ON	2004/05/05 15:42
S34	428	((cmp or polish or polishing or planarize or planarizing) and (chamfer\$4)) and semiconductor	USPAT	OR	ON	2004/05/05 15:42
S35	301	((cmp or polish or polishing or planarize or planarizing) and (chamfer\$4)) and semiconductor) and (etch or etching)	USPAT	OR	ON	2005/03/17 12:26

S36	281	(((((cmp or polish or polishing or planarize or planarizing) and (chamfer\$4)) and semiconductor) and (etch or etching)) and @ay<="2001"	USPAT	OR	ON	2004/05/05 15:42
S37	265	(((((cmp or polish or polishing or planarize or planarizing) and (chamfer\$4)) and semiconductor) and (etch or etching)) and @ay<="2001") not (((((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) same (edge or pivot))) and (slurry or abrasive)) not (((((((cmp or polish or polishing or planarize or planarizing) and (edge or pivot)) and semiconductor) and (etch or etching) and (mask or hard\$1mask)) and ((cmp or polish or polishing or planarize or planarizing) with (edge or pivot))) and @ay<="2001") and (slurry or abrasive))) or (Matsubara-Yoshihisa.in. and semiconductor) or (((((cmp or polish or polishing or planarize or planarizing) with (edge or bevel\$3)) and semiconductor and @ay<="2001") and (slurry or abrasive)) and (mask or hard\$1mask)))	USPAT	OR	ON	2004/05/05 15:43
S38	9	("5152857"   "5254830"   "5374564"   "5494862"   "5766065"   "5928066"   "5942445"   "6312797"   "6352927").PN.	USPAT	OR	ON	2004/05/05 15:45
S39	17	("4294651"   "4372803"   "4940510"   "5233218"   "5389551"   "5426073"   "5445706"   "5449532"   "5622875"   "5893982"   "5945351"   "6033997"   "6080675"   "6099748"   "6150969"   "6294469"   "6335267"   "2001/0014570"   "2001/0039101"   "2002/0004305").PN.	USPAT	OR	ON	2004/05/05 15:48
S40	1	"6335267".pn.	USPAT	OR	ON	2004/05/06 12:59